



High-end Power Semiconductor Manufacturer

KP1500A 1000V-1800V

Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications



Mean on-state current		I _{TAV}	1500 A		
Repetitive peak off-state voltage		V _{DRM}	1000 – 1800 V		
Repetitive peak reverse voltage		V _{RRM}			
Turn-off time		t _q	160 µs		
V _{DRM} , V _{RRM} , V	1000	1200	1400	1600	1800
Voltage code	10	12	14	16	18
T _j , °C	-60 – 125				

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	1500	T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	2355	T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	28.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 50 Hz (t _p =10 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			32.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 60 Hz (t _p =8.3 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² s·10 ³	30.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 50 Hz (t _p =10 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			35.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 60 Hz (t _p =8.3 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	1000 – 1800	T _{j min} < T _j <T _j max; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	1100 – 1900	T _{j min} < T _j <T _j max; 180° half-sine wave; 50 Hz;single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.75·V _{DRM} 0.75·V _{RRM}	T _j =T _j max; Gate open	

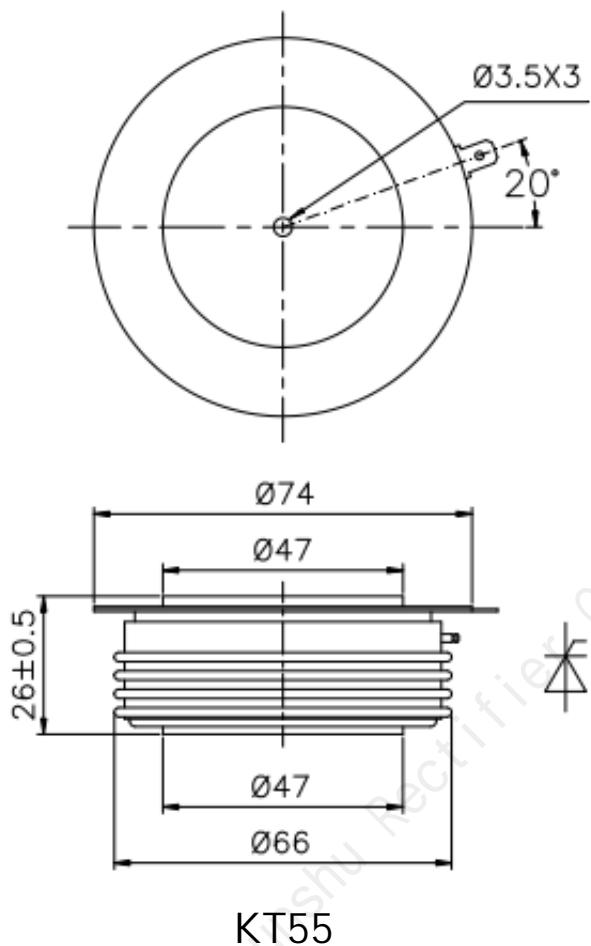
TRIGGERING				
I _{FGM}	Peak forward gate current	A	8	T _j =T _j max
V _{RGM}	Peak reverse gate voltage	V	5	
P _G	Gate power dissipation	W	4	T _j =T _j max for DC gate current
SWITCHING				
(di _T /dt) _{crit}	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/ μ s	1000	T _j =T _j max; V _D =0.67V _{DRM} ; I _{TM} =2 I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μ s; di _G /dt≥1 A/ μ s
THERMAL				
T _{stg}	Storage temperature	°C	-60–125	
T _j	Operating junction temperature	°C	-60–125	
MECHANICAL				
F	Mounting force	kN	24.0–28.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
V _{TM}	Peak on-state voltage, max	V	1.80	T _j =25 °C; I _{TM} =5024 A
V _{T(TO)}	On-state threshold voltage, max	V	0.85	T _j =T _j max;
r _T	On-state slope resistance, max	mΩ	0.185	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}
I _L	Latching current, max	mA	1500	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μ s; di _G /dt≥1 A/ μ s
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open
BLOCKING				
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	150	T _j =T _j max; V _D =V _{DRM} ; V _R =V _{RRM}
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	1000	T _j =T _j max; V _D =0.67V _{DRM} ; Gate open
TRIGGERING				
V _{GT}	Gate trigger direct voltage, max	V	2.50 2.00	T _j =25 °C T _j = T _j max
I _{GT}	Gate trigger direct current, max	mA	250 200	T _j = 25 °C T _j = T _j max
V _{GD}	Gate non-trigger direct voltage, min	V	0.25	T _j =T _j max; V _D =0.67V _{DRM} ;
I _{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current
SWITCHING				
t _{gd}	Delay time	μ s	2.00	T _j =25 °C; V _D =0.4V _{DRM} ; I _{TM} =I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μ s; di _G /dt≥1 A/ μ s
t _q	Turn-off time ²⁾ , max	μ s	160	dv _D /dt=50 V/ μ s; T _j =T _j max; I _{TM} =2000 A; di _R /dt=-10 A/ μ s; V _R =100V; V _D =0.67V _{DRM}
Q _{rr}	Total recovered charge, max	μ C	2400	T _j =T _j max; I _{TM} =2000 A;
t _{rr}	Reverse recovery time, max	μ s	28.0	di _R /dt=-10 A/ μ s ;
I _{rrM}	Peak reverse recovery current, max	A	170	V _R =100 V

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0180	Direct current	Double side cooled
R_{thjc-A}			0.0396		Anode side cooled
R_{thjc-K}			0.0324		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0040	Direct current	
MECHANICAL					
W	Weight, typ	g	510		
D_s	Surface creepage distance	mm (inch)	31.60 (1.244)		
D_a	Air strike distance	mm (inch)	16.50 (0.649)		

OVERALL DIMENSIONS



KT55

All dimensions in millimeters

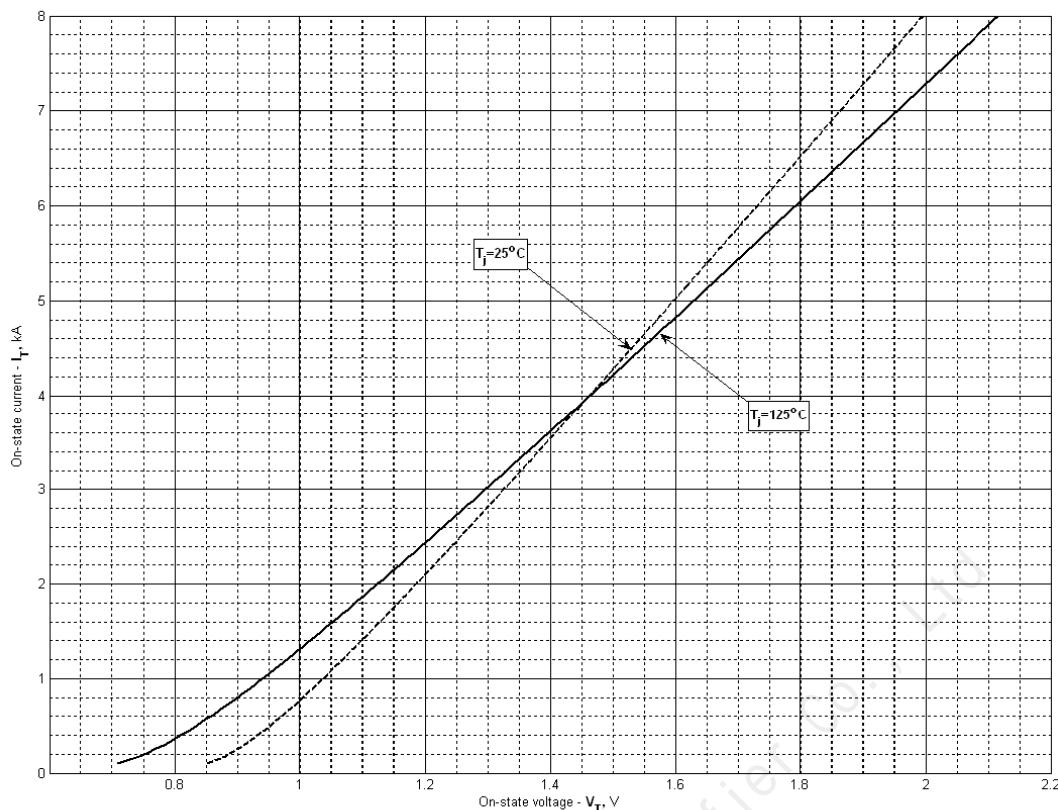


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	T _J = 25°C	T _J = T _{j max}
A	0.764304	0.591211
B	0.097013	0.114615
C	-0.186669	-0.249310
D	0.305434	0.407929

On-state characteristic model (see Fig. 1)

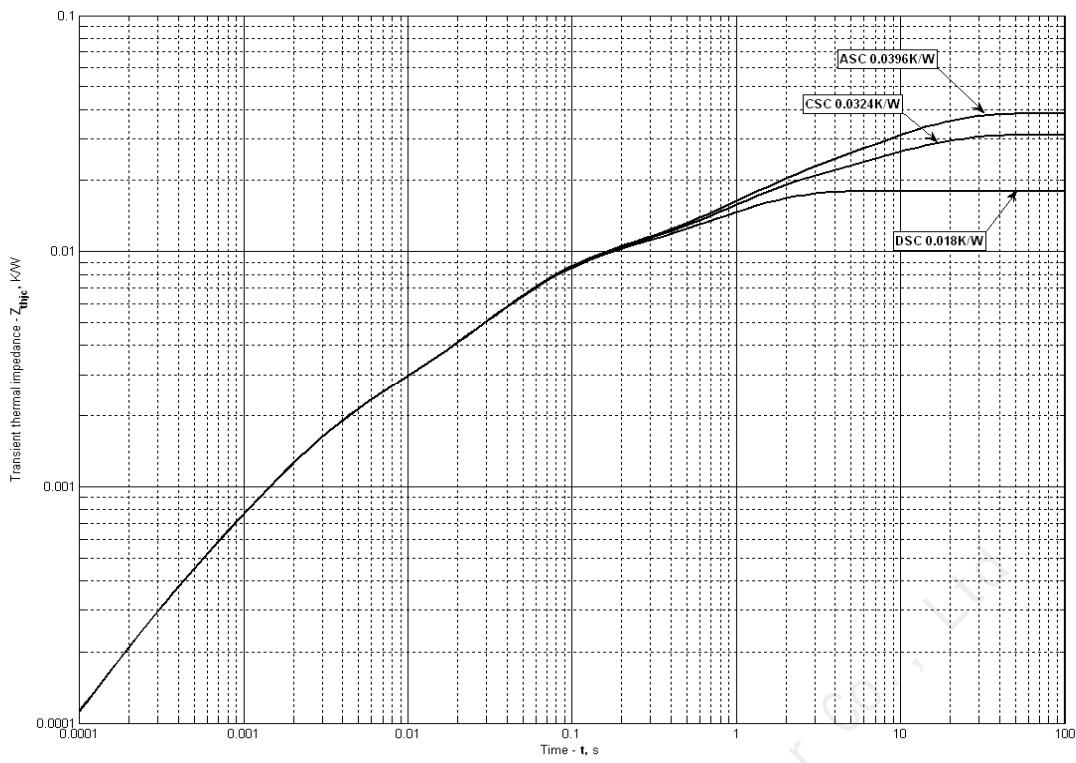


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.009241	0.006037	0.001231	0.001054	0.0003396	0.00009575
τ_i , s	0.9673	0.04967	0.002733	0.07734	0.001638	0.0002248

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.01318	0.009281	0.006055	0.001018	0.001535	0.0001182
τ_i , s	9.745	1.028	0.05591	0.03732	0.002468	0.0002687

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.02041	0.009325	0.006949	0.0001252	0.001516	0.0001119
τ_i , s	9.752	1.065	0.05344	0.01407	0.002421	0.0002554

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

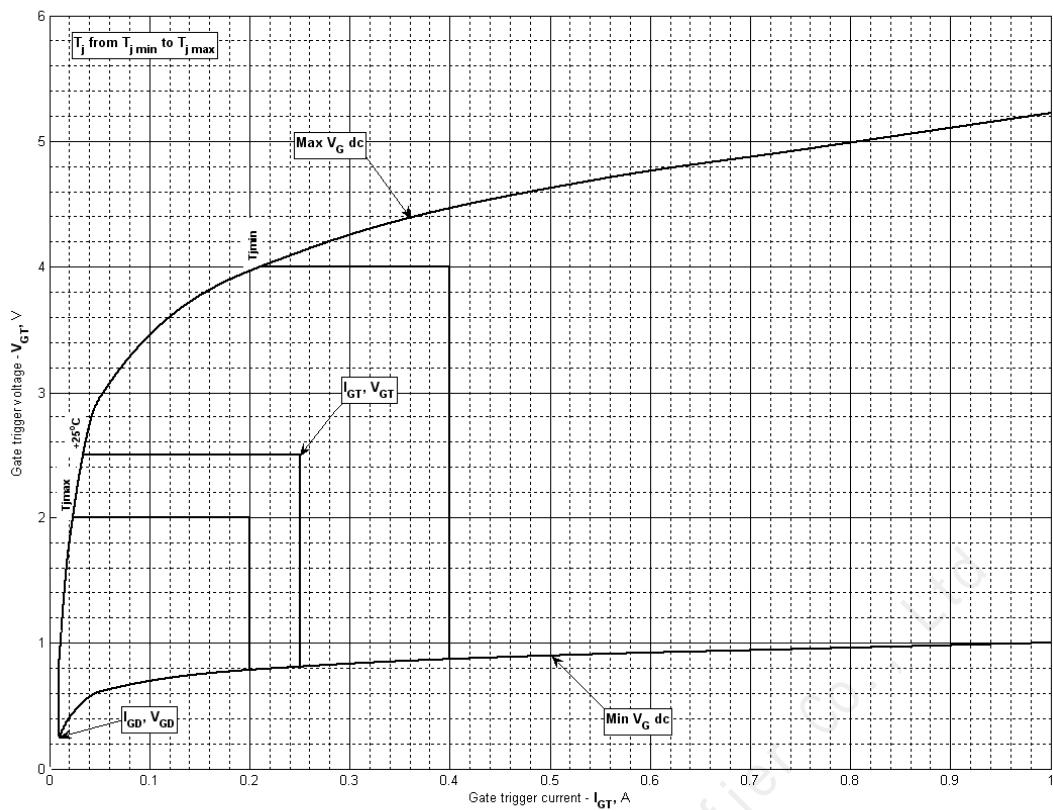


Fig 3 – Gate characteristics – Trigger limits

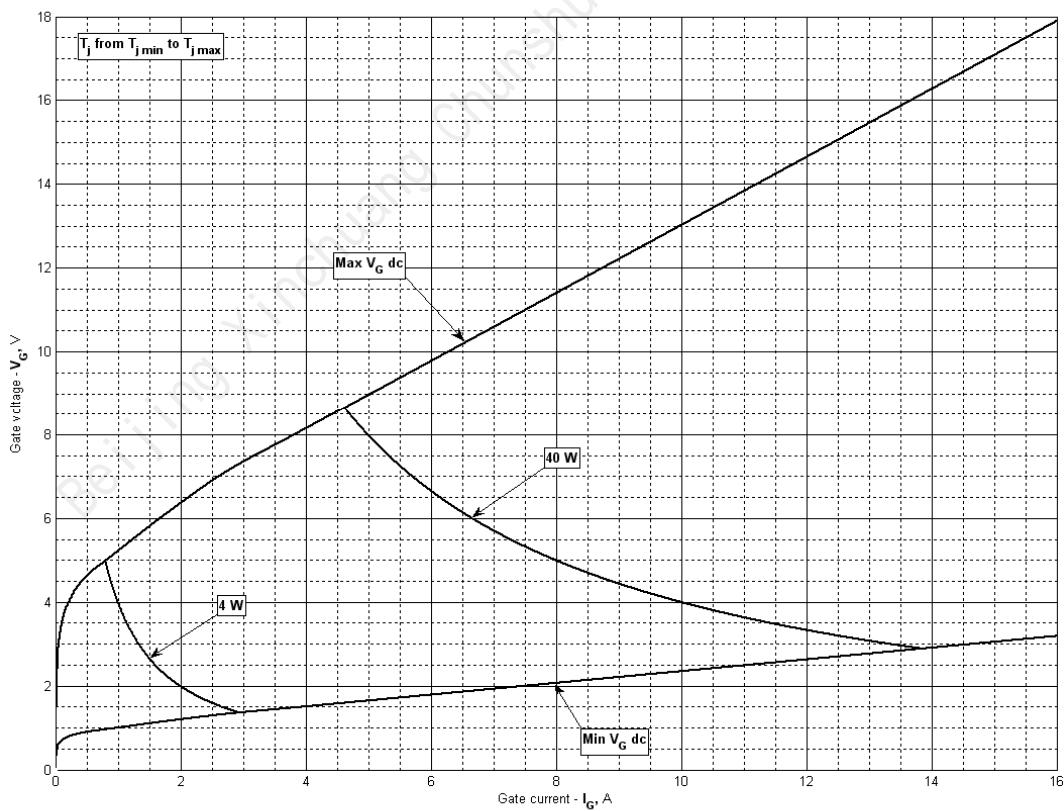


Fig 4 - Gate characteristics –Power curves

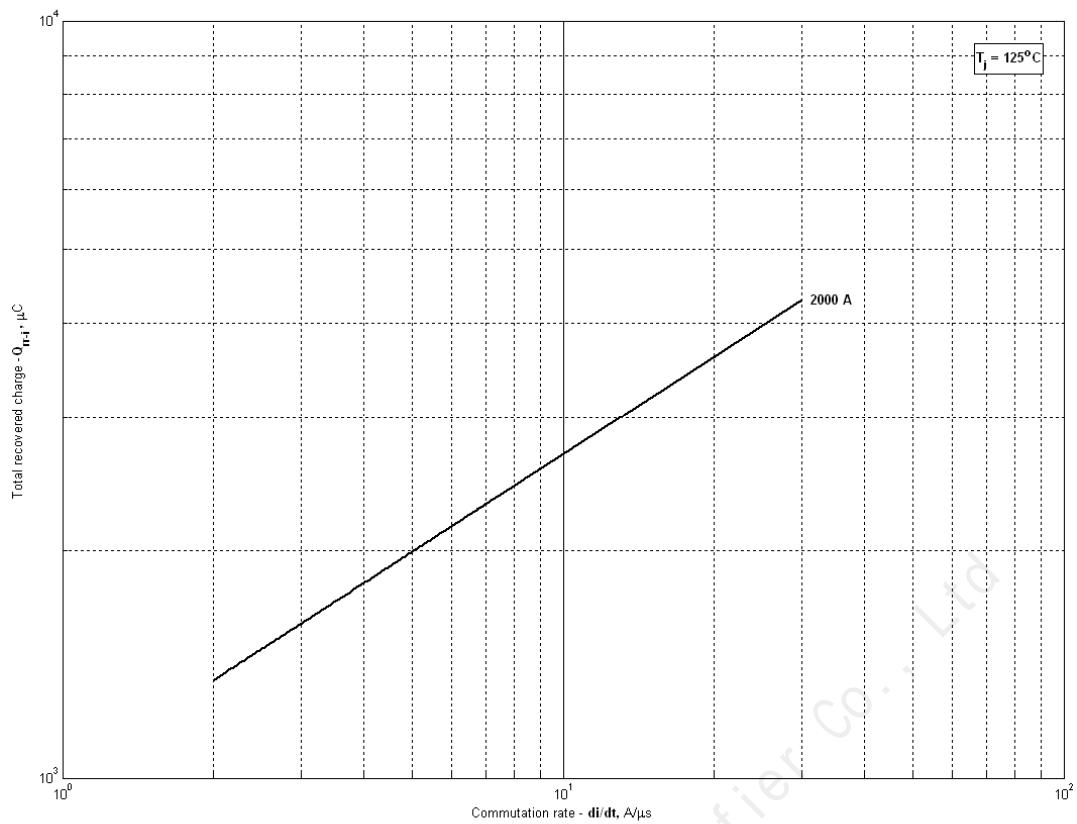


Fig 5 – Total recovered charge, Q_{rr-i} (integral)

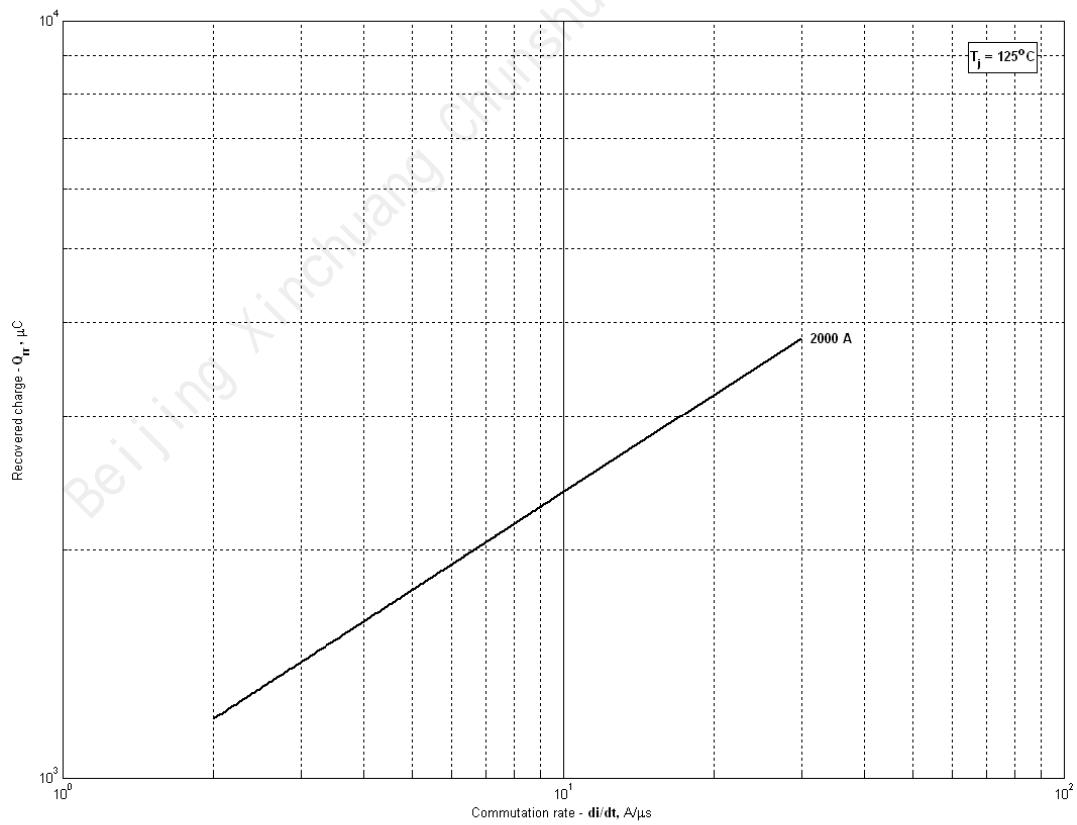


Fig 6 - Recovered charge, Q_{rr} (linear)

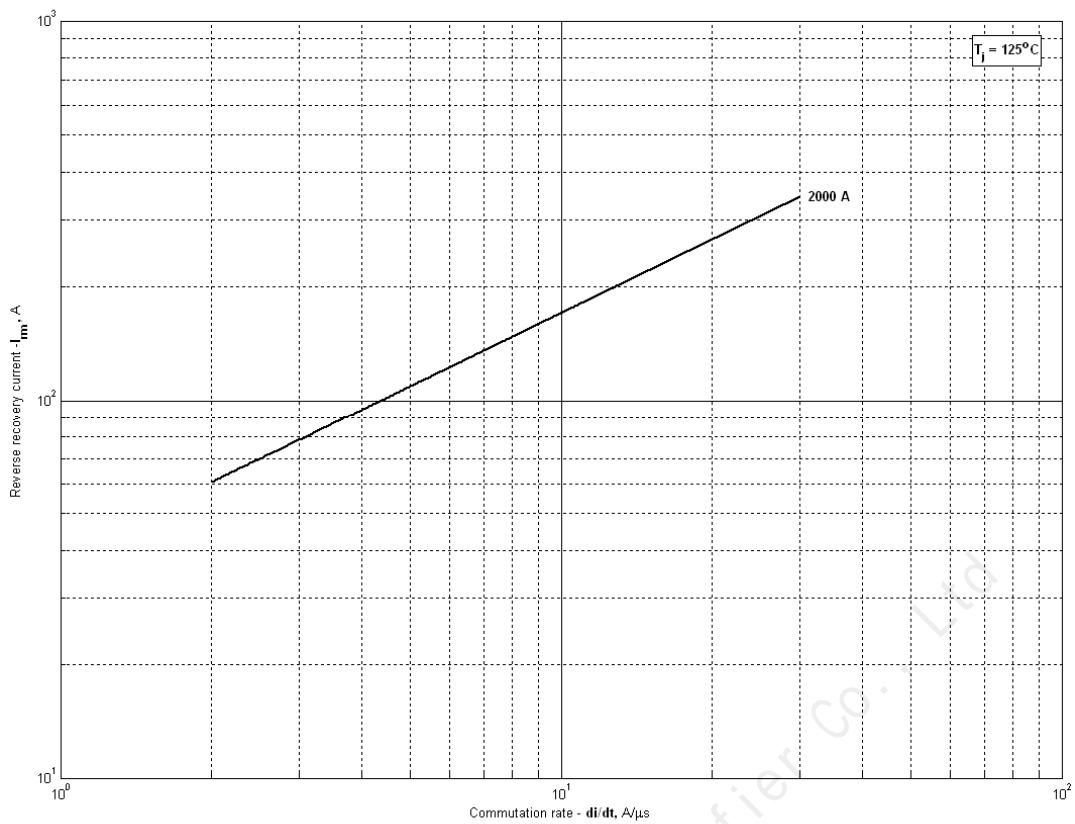


Fig 7 – Peak reverse recovery current, I_{rm}

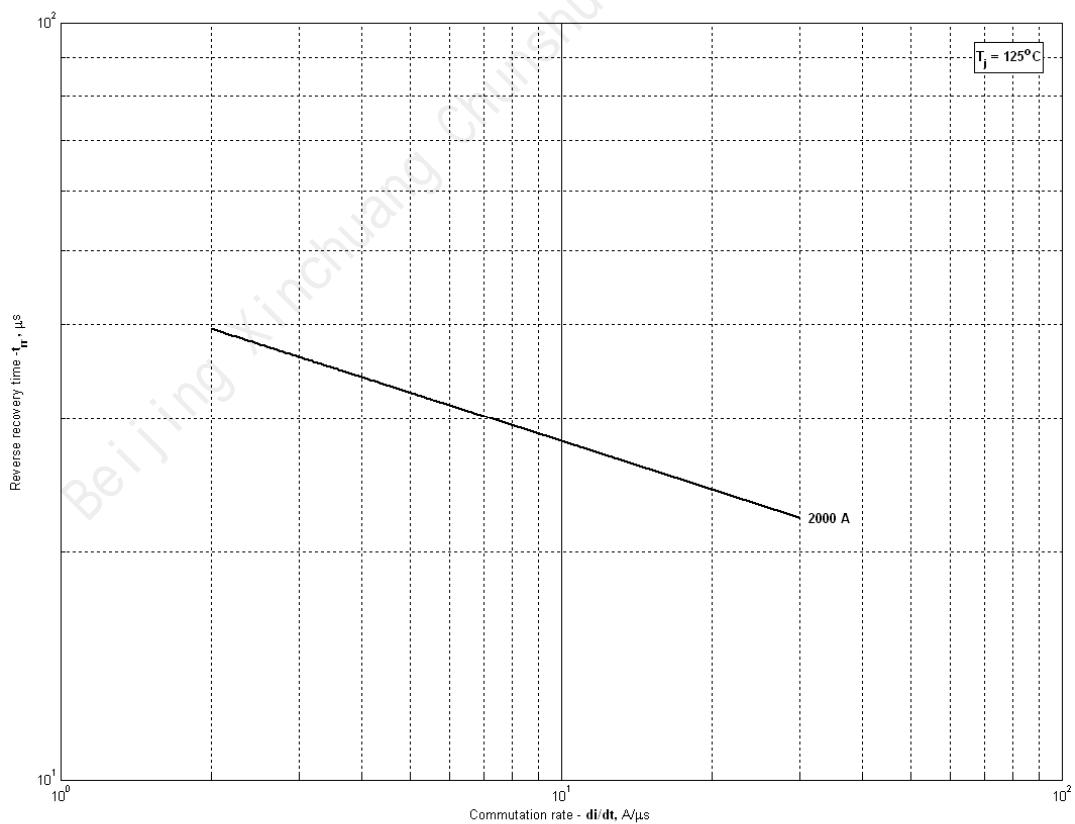


Fig 8 – Maximum recovery time, t_{rr} (linear)

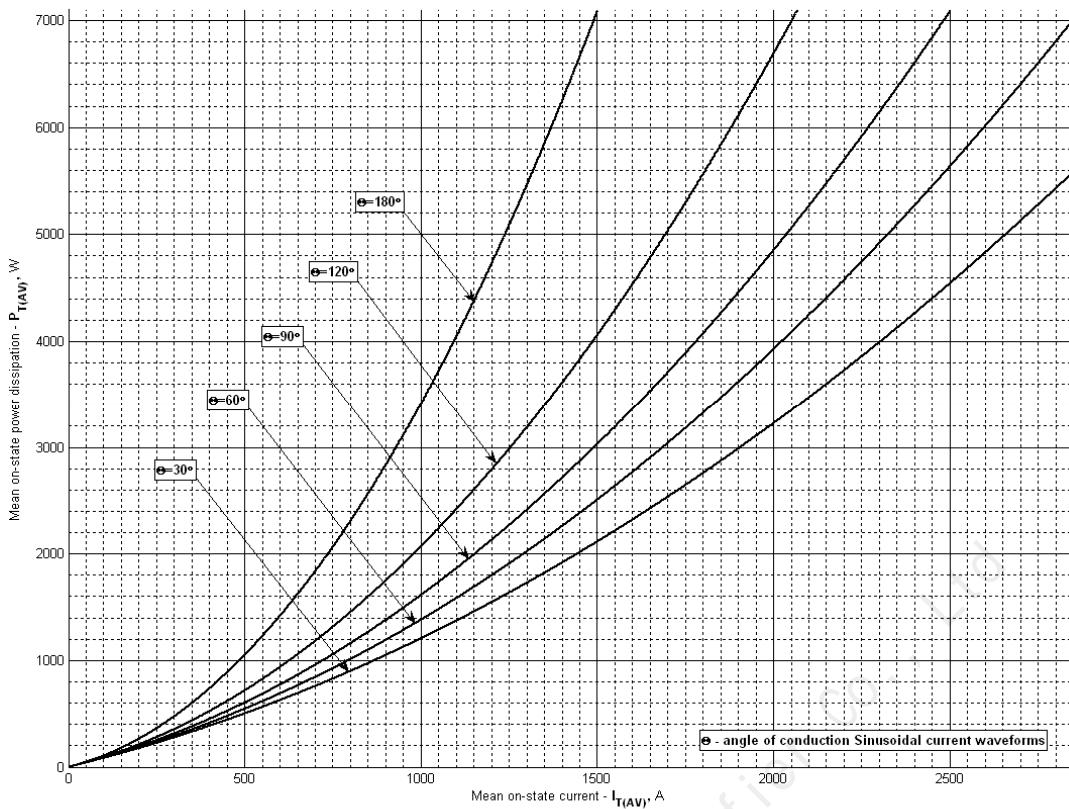


Fig 9 – On-state power loss (sinusoidal current waveforms)

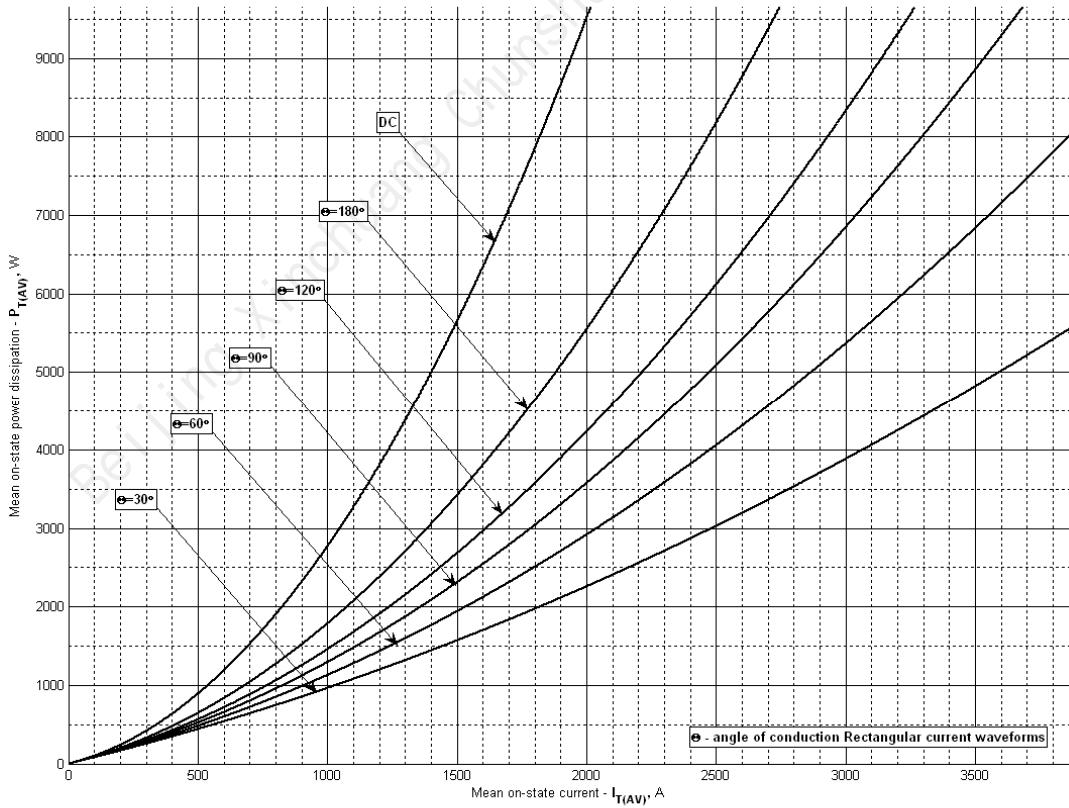


Fig 10 – On-state power loss (rectangular current waveforms)

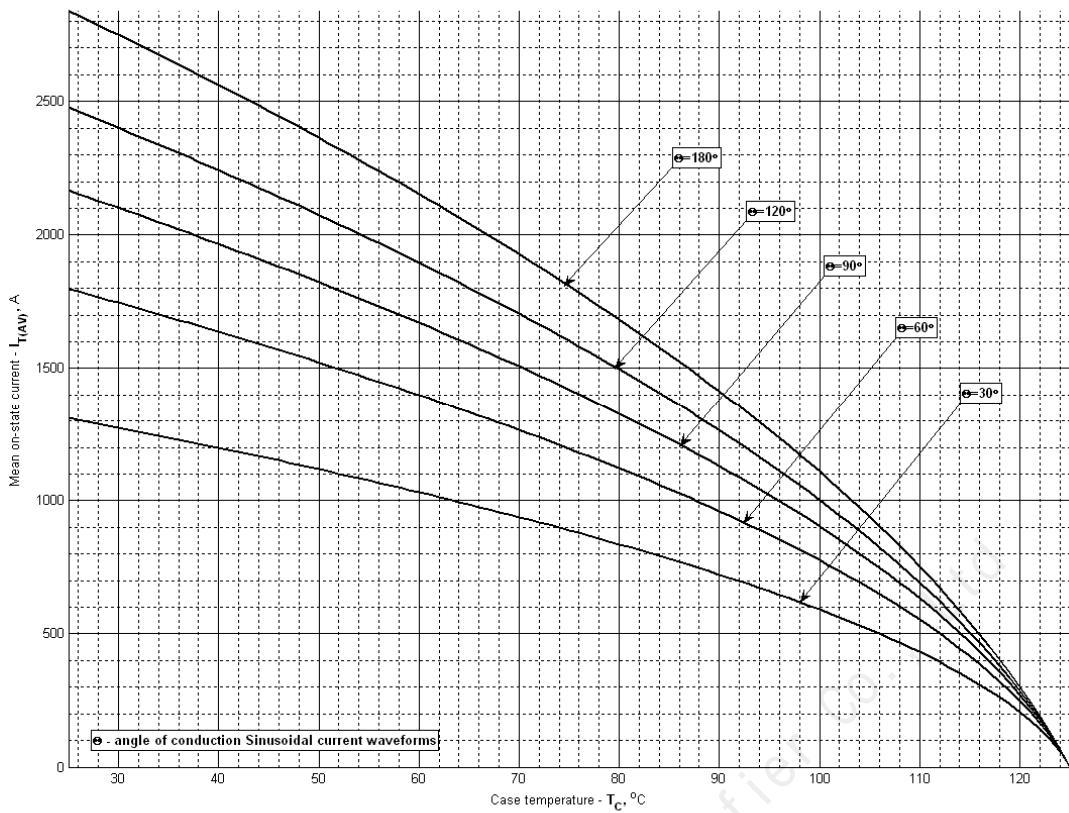


Fig 11 – Maximum case temperature DSC (sinusoidal current waveforms)

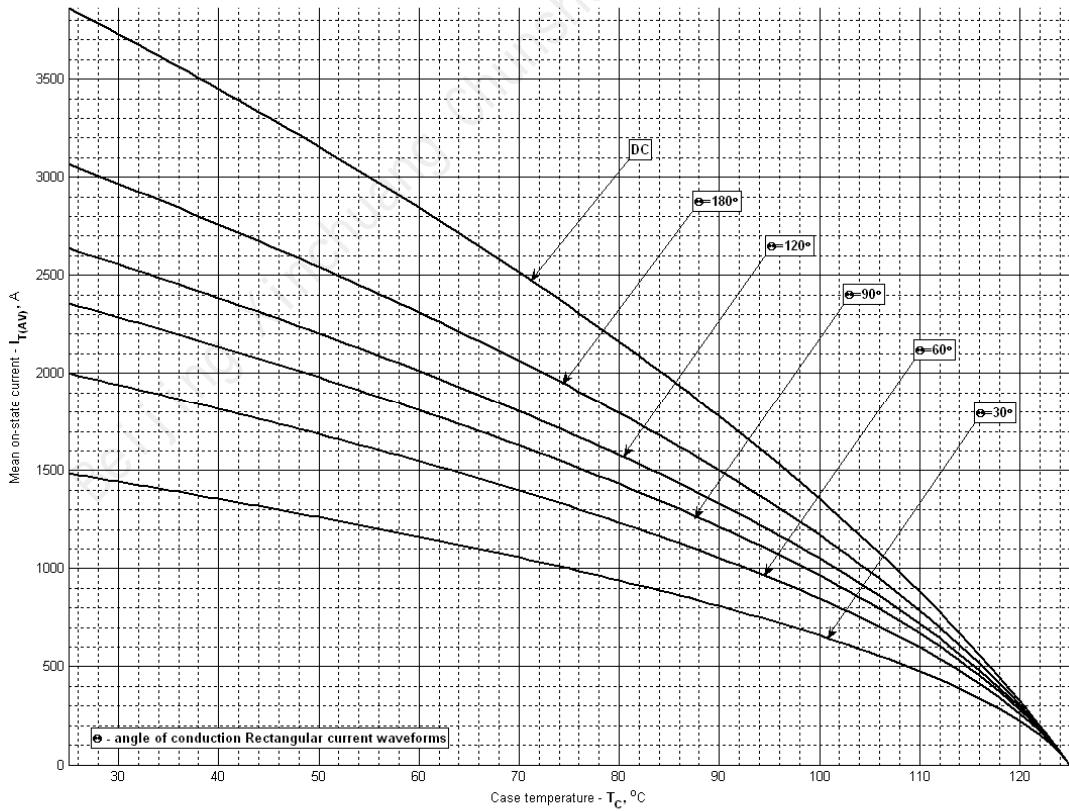


Fig 12 – Maximum case temperature DSC (rectangular current waveforms)

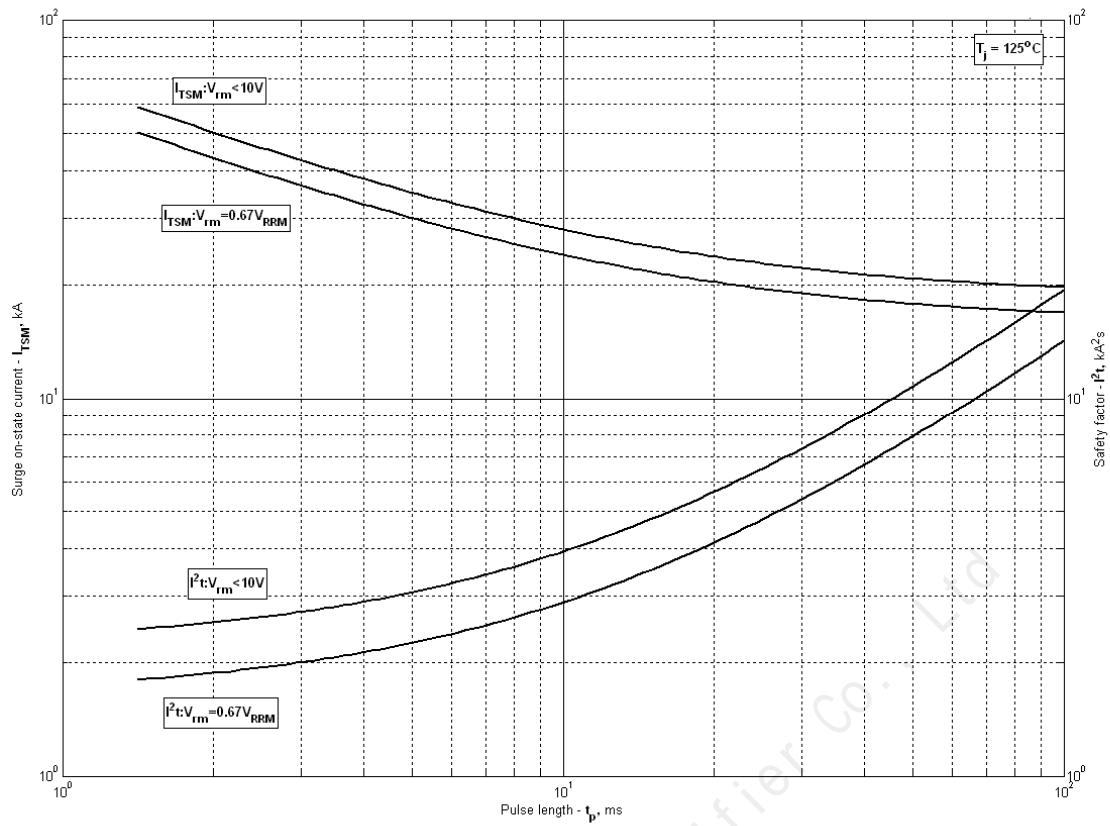


Fig 13 – Maximum surge and I^2t ratings

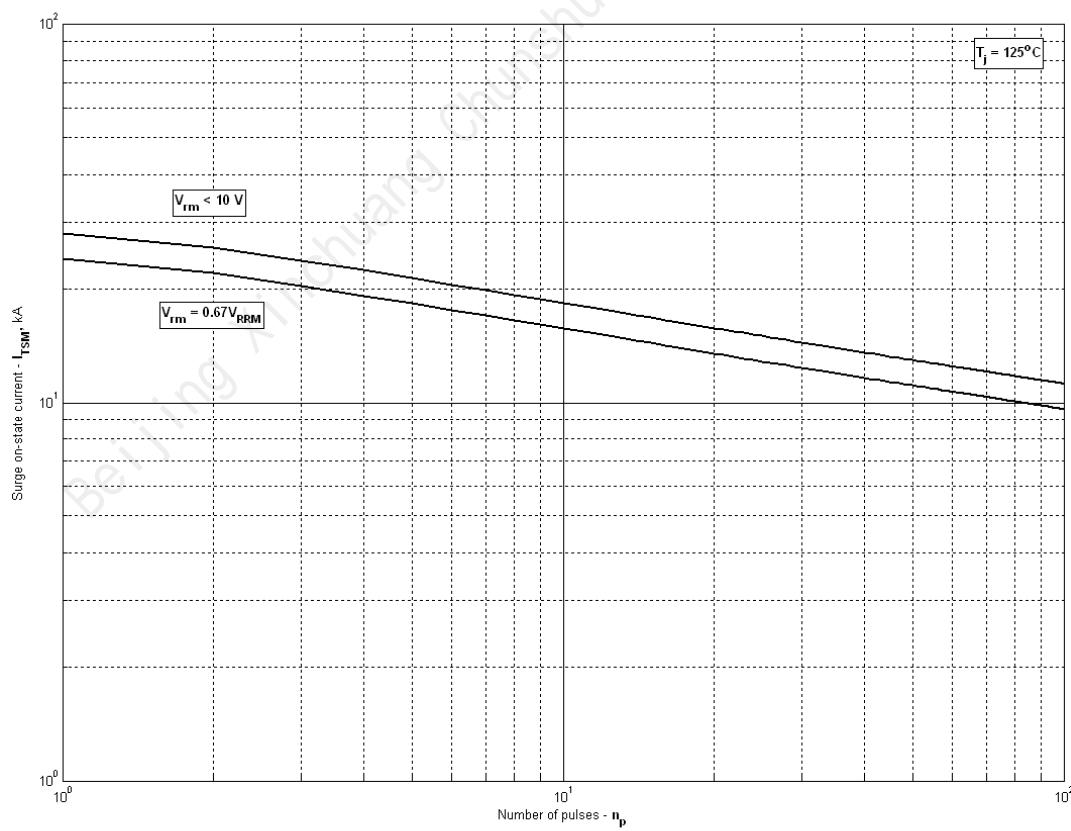


Fig 14 – Maximum surge ratings